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Kunihiro Hosono
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EUV Mask I

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Osamu Suga, Semiconductor Leading Edge Technologies, Inc.
(Japan)
Banqiu Wu, Applied Materials, Inc. (United States)

EUV Mask II

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(Japan)

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Banqiu Wu, Applied Materials, Inc. (United States)

Nano Imprint and Patterned Media

Morihisa Hougá, Dai Nippon Printing Company, Ltd. (Japan)

Youichi Usui, HOYA Corporation (Japan)

Material and Process

Toshio Konishi, Toppan Printing Company, Ltd. (Japan)

Koji Murano, Toshiba Corporation (Japan)

Thomas B. Faure, IBM Corporation (United States)

Process and Repair

Toshio Konishi, Toppan Printing Company, Ltd. (Japan)

Koji Murano, Toshiba Corporation (Japan)

Thomas B. Faure, IBM Corporation (United States)

Pattern Generation

Noriaki Nakayamada, NuFlare Technology, Inc. (Japan)

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Metrology and Inspection

Tatsuya Tomita, Dai Nippon Printing Company, Ltd. (Japan)

Shinji Akima, Toppan Printing Company, Ltd. (Japan)

Byung Gook Kim, SAMSUNG Electronics Company, Ltd.
(Korea, Republic of)

Mask-related Lithography

Minoru Sugawara, Sony Corporation (Japan)

Steffen Schulze, Mentor Graphics Corporation (United States)

EDA, DFM, and MDP

Kokoro Kato, SII NanoTechnology Inc. (Japan)

Nobuyuki Nishiguchi, Semiconductor Technology Academic Research
Center (Japan)